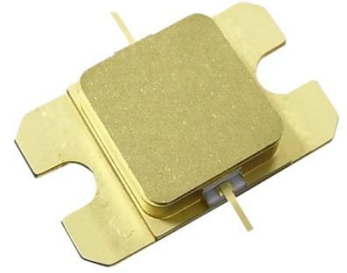


■ Features

- High Output Power: P5dB=45.0dBm (Typ.)
- High Linear Gain: GL=15.0dB (Typ.)
- High Power Added Efficiency: PAE=41% (Typ.)
- Broad Band: 5.85 to 6.75GHz
- Impedance Matched Zin/Zout = 50ohm
- Hermetically Sealed Package



■ Description

The SGK5867-30C is a high power GaN-HEMT that is internally matched for standard communication bands to provide optimum power and gain in a 50ohm system.

ABSOLUTE MAXIMUM RATING (Case Temperature T_c=25 deg.C)

Item	Symbol	Rating	Unit
Drain-Source Voltage	V _{DS}	26	V
Gate-Source Voltage	V _{GS}	-10	V
Total Power Dissipation	P _T	86.5	W
Storage Temperature	T _{sta}	-55 to +125	deg.C
Channel Temperature	T _{ch}	+250	deg.C
Case Temperature	T _c	-40 to +125	deg.C

RECOMMENDED OPERATING CONDITION

Item	Symbol	Condition	Limit	Unit
Drain-Source Voltage	V _{DS}		<=24	V
Forward Gate Current	I _{GF}	Rg=100ohm	<=4.4	mA
Reverse Gate Current	I _{GR}	Rg=100ohm	>=-2.3	mA
Channel Temperature	T _{ch}		<+193	deg.C

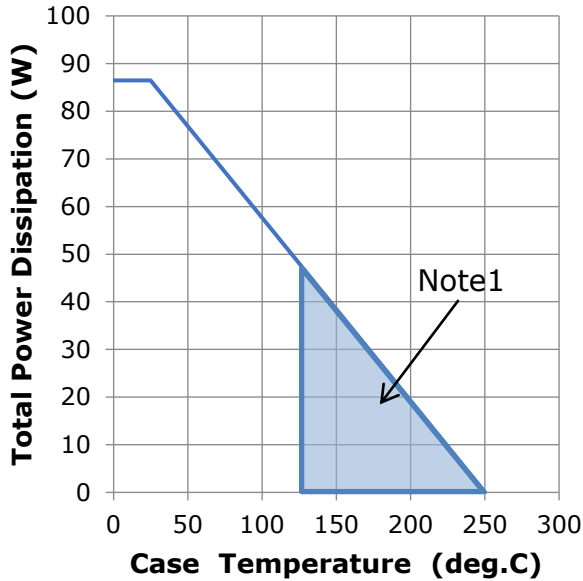
ELECTRICAL CHARACTERISTICS (Case Temperature T_c=25 deg.C)

Item	Symbol	Condition	Limit			Unit
			Min.	Typ.	Max.	
Saturated Drain Current	I _{DSS}	V _{DS} =10V, V _{GS} =0V	-	8.3	-	A
Trans Conductance	G _m	V _{DS} =24V, I _{DS} =0.96A	-	2.2	-	S
Pinch-off Voltage	V _p	V _{DS} =24V, I _{DS} =0.96mA	-2.5	-4.0	-5.5	V
Output Power at 5dB G.C.P.	P _{5dB}	V _{DS} =24V(typ.) I _{DS(DC)} =1.75A(typ.) f=5.85 to 6.75 GHz V _{gs} -constant	44.0	45.0	-	dBm
Linear Gain at Pin=21.5dBm	GL		12.5	15.0	-	dB
Drain Current at 5dB G.C.P.	I _{DSR}	f=5.85 to 6.75 GHz V _{gs} -constant	-	3.2	4.0	A
Power Added Efficiency at 3dB G.C.P.	PAE		-	41	-	%
Gain Flatness	ΔG		-	-	1.6	dB
3rd Order Inter Modulation Distortion	IM ₃	f=6.75GHz Δf=10MHz, 2-tone Test Pout=29.5dBm (S.C.L.)	-40.0	-42.0	-	dBc
Thermal Resistance	R _{th}	Channel to Case	-	2.2	2.6	deg.C/W
Channel Temperature Rise	ΔT _{ch}	(V _{DS} × I _{DSR} - Pout + Pin) × R _{th}	-	83	150	deg.C

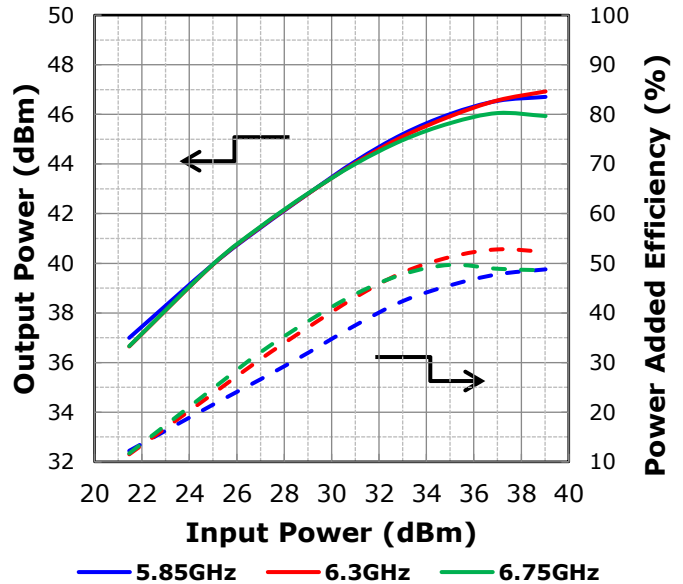
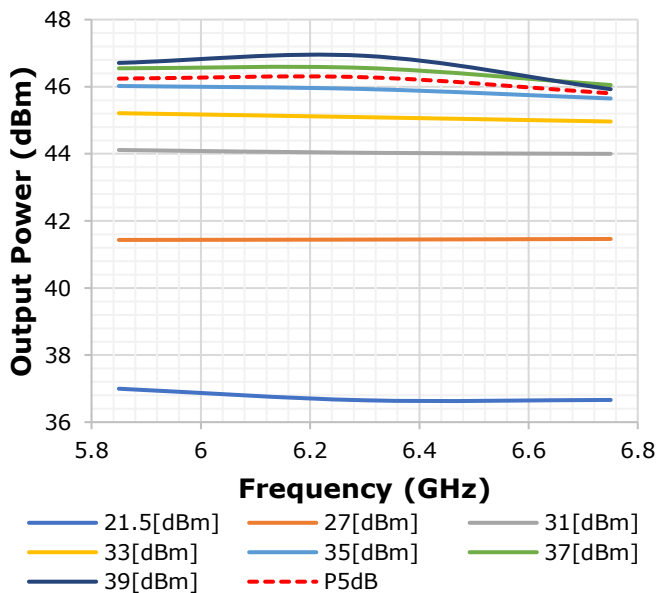
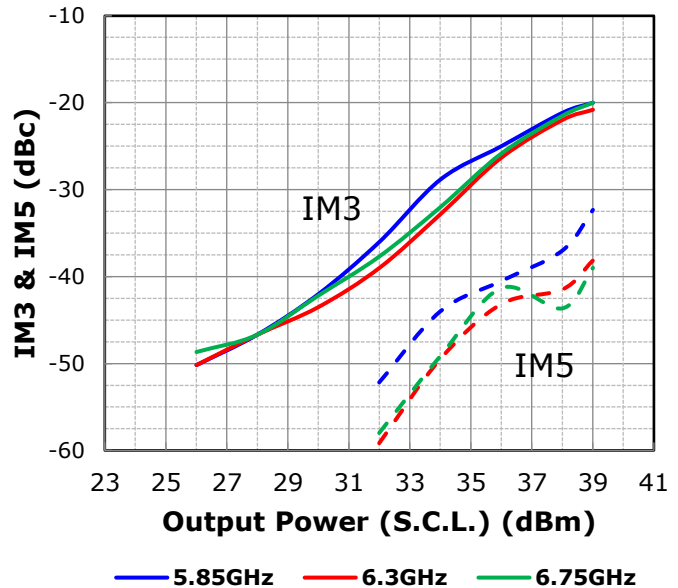
G.C.P. : Gain Compression Point, S.C.L. : Single Carrier Level

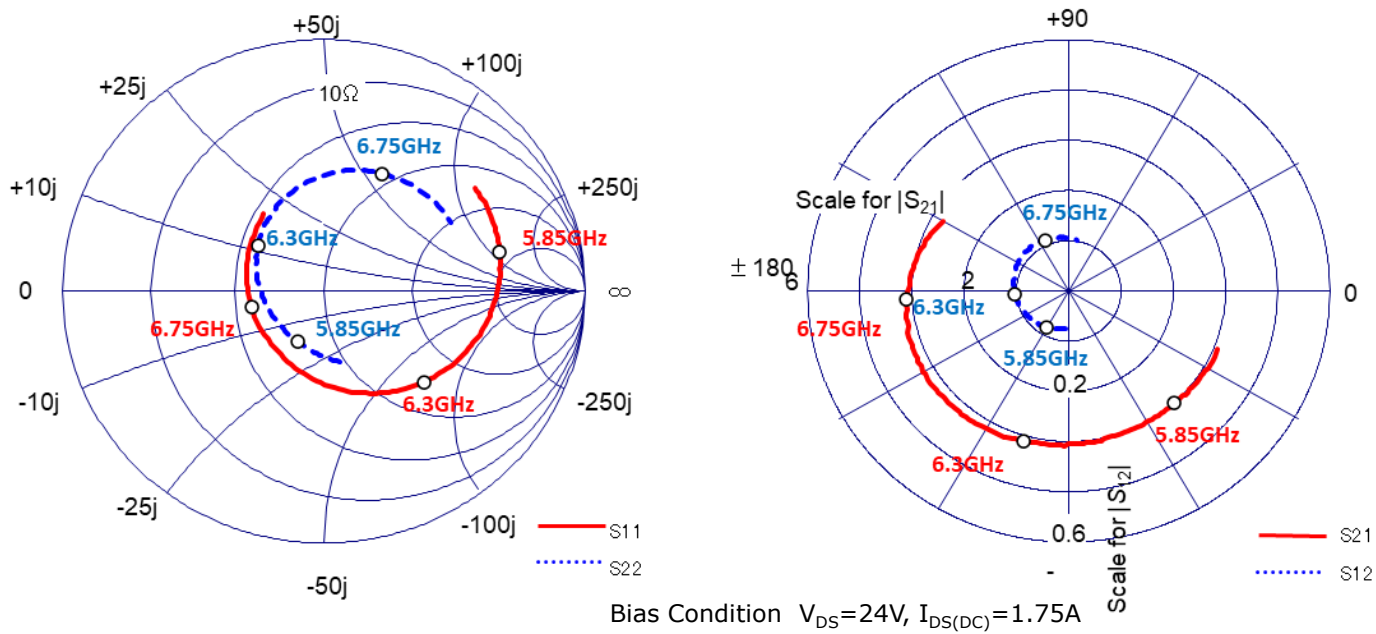
CASE STYLE	IBK
RoHS Compliance	YES
ESD	Class 2
	2000V to < 4000V

Note : Based on ANSI/ESDA/JEDEC JS-001-2012(C=100pF, R=1.5kohm)

RF Characteristics
Power Derating Curve


Note 1: Shaded area exceeds Maximum Case Operating Temperature (See Page1)

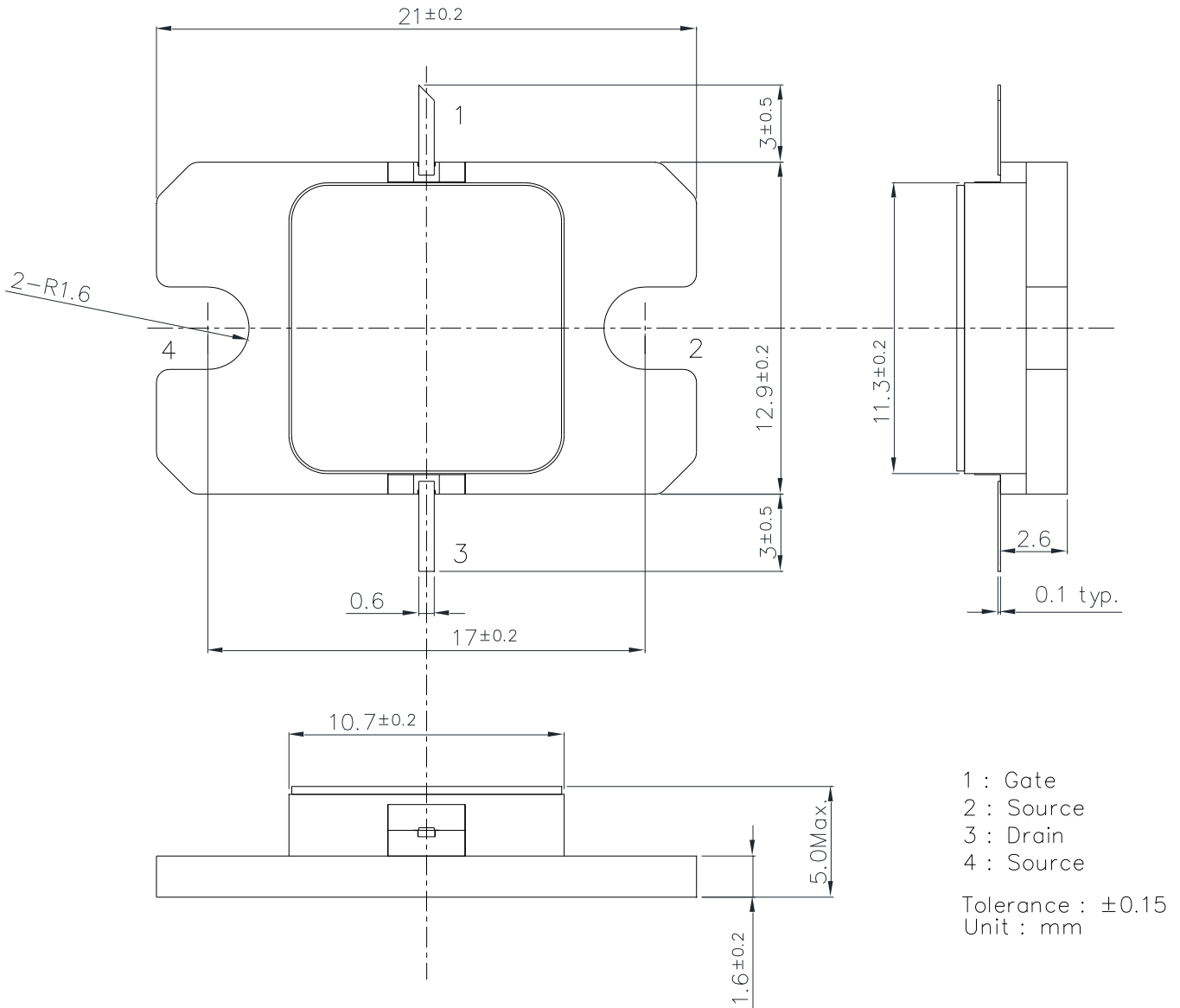
Input Power vs. Output Power and Power Added Efficiency
 $V_{DS}=24V, I_{DS(DC)}=1.75A$

Output Power vs. Frequency
 $V_{DS}=24V, I_{DS(DC)}=1.75A$

IMD vs. Output Power (S.C.L.)
 $V_{DS}=24V, I_{DS(DC)}=1.75A, \Delta f=10MHz$


● S-Parameter


Freq.	S11		S21		S12		S22	
	MAG	ANG	MAG	ANG	MAG	ANG	MAG	ANG
5.65GHz	0.708	35.3	6.166	-22.2	0.060	-95.2	0.288	-77.9
5.7GHz	0.710	29.7	6.166	-28.8	0.062	-101.0	0.266	-86.4
5.85GHz	0.692	13.0	6.026	-47.8	0.067	-120.0	0.224	-116.0
6.0GHz	0.653	-3.8	6.026	-66.7	0.072	-139.0	0.216	-152.0
6.1GHz	0.621	-16.0	6.095	-79.4	0.076	-151.0	0.234	-175.0
6.2GHz	0.578	-28.9	6.166	-92.7	0.079	-164.0	0.266	164.0
6.3GHz	0.528	-43.4	6.237	-106.0	0.082	-177.0	0.309	144.0
6.4GHz	0.463	-60.4	6.310	-121.0	0.086	169.0	0.356	127.0
6.5GHz	0.393	-81.7	6.383	-136.0	0.089	154.0	0.408	109.0
6.6GHz	0.324	-110.0	6.383	-152.0	0.090	138.0	0.457	91.1
6.75GHz	0.282	-167.0	6.237	-177.0	0.089	114.0	0.519	64.4
6.9GHz	0.348	140.0	5.754	158.0	0.084	89.2	0.555	37.9
6.95GHz	0.384	127.0	5.559	150.0	0.082	81.2	0.558	29.2

● Package Out line

Case Style : IBK



For Safety, Observe the Following Procedures Environmental Management

- Do not put this product into the mouth.
- Do not alter the form of this product into a gas, powder, or liquid through burning, crushing, or chemical processing as these by-products are dangerous to the human body if inhaled, ingested, or swallowed.
- Respect all applicable laws of the country when discarding this product.
This product must be disposed in accordance with methods specified by applicable hazardous waste procedures.

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